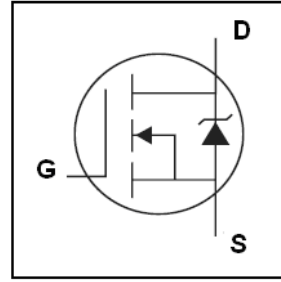


### Features

- ◆ Ron(typ.)=30 mΩ @V<sub>GS</sub>=4.5V
- ◆ Low On-Resistance
- ◆ 150°C Operating Temperature
- ◆ Fast Switching
- ◆ Lead-Free, RoHS Compliant



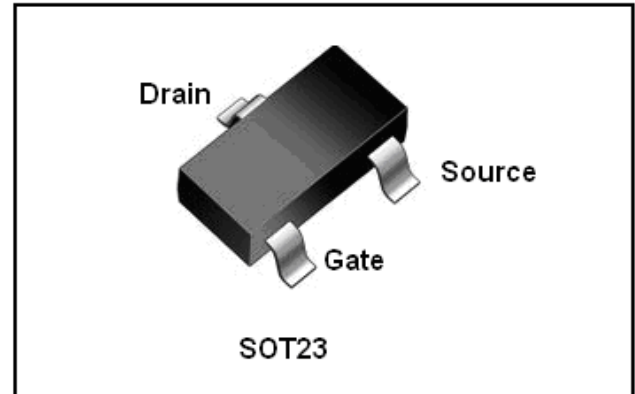
V<sub>DSS</sub>=30V

R<sub>DS(on)</sub>=27mΩ @V<sub>GS</sub>=4.5V

R<sub>DS(on)</sub>=35mΩ @V<sub>GS</sub>=2.5V

### Description

VS3400BC designed by the trench processing techniques to achieve extremely low on-resistance. And fast switching speed and improved transfer effective. These features combine to make this design an extremely efficient and reliable device for variety of DC-DC applications.



### Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T<sub>A</sub>) is 25°C, unless otherwise specified.

Symbol	Parameter		Rating	Unit
<b>Common Ratings (T<sub>A</sub>=25°C Unless Otherwise Noted)</b>				
V <sub>GS</sub>	Gate-Source Voltage		±12	V
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage		30	V
T <sub>J</sub>	Maximum Junction Temperature		150	°C
T <sub>STG</sub>	Storage Temperature Range		-50 to 150	°C
I <sub>S</sub>	Diode Continuous Forward Current	T <sub>A</sub> =25°C	1	A
<b>Mounted on Large Heat Sink</b>				
I <sub>DM</sub>	Pulse Drain Current Tested <sup>①</sup>	T <sub>A</sub> =25°C	20	A
I <sub>D</sub>	Continuous Drain Current(VGS=10V)	T <sub>A</sub> =25°C	5.8 <sup>①</sup>	A
		T <sub>A</sub> =100°C	3.6	
P <sub>D</sub>	Maximum Power Dissipation	T <sub>A</sub> =25°C	1.20	W
R <sub>θJA</sub>	Thermal Resistance Junction-Ambient		105	°C/W

Symbol	Parameter	Condition	Min	Typ	Max	Unit
<b>Static Electrical Characteristics @ T<sub>A</sub> = 25°C (unless otherwise stated)</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V I <sub>D</sub> =250μA	30	--	--	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current(T <sub>J</sub> =25°C)	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	--	--	1	μA
	Zero Gate Voltage Drain Current(T <sub>J</sub> =125°C)	V <sub>DS</sub> =30V,V <sub>GS</sub> =0V	--	--	100	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>GS</sub> =±12V,V <sub>DS</sub> =0V	--	--	±100	nA
V <sub>GS(TH)</sub>	Gate Threshold Voltage	V <sub>DS</sub> =V <sub>GS</sub> ,I <sub>D</sub> =250μA	0.60	0.85	1.20	V
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>②</sup>	V <sub>GS</sub> =4.5V, I <sub>D</sub> =5.8A	--	27	35	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>②</sup>	V <sub>GS</sub> =3.3V, I <sub>D</sub> =4.5A	--	29	38	mΩ
R <sub>DS(ON)</sub>	Drain-Source On-State Resistance <sup>②</sup>	V <sub>GS</sub> =2.5V, I <sub>D</sub> =4.5A	--	35	45	mΩ
<b>Dynamic Electrical Characteristics @ T<sub>A</sub> = 25°C (unless otherwise stated)</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =15V,V <sub>GS</sub> =0V, f=1MHz	--	635	--	pF
C <sub>oss</sub>	Output Capacitance		--	135	--	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		--	40	--	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>DS</sub> =15V,I <sub>D</sub> =5.8A, V <sub>GS</sub> =4.5V	--	10.5	--	nC
Q <sub>gs</sub>	Gate-Source Charge		--	1.6	--	nC
Q <sub>gd</sub>	Gate-Drain Charge		--	2.7	--	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>DD</sub> =15V, I <sub>D</sub> =2.8A, R <sub>G</sub> =3.3Ω, V <sub>GS</sub> =4.5V	--	7.2	--	nS
t <sub>r</sub>	Turn-on Rise Time		--	15	--	nS
t <sub>d(off)</sub>	Turn-Off Delay Time		--	36	--	nS
t <sub>f</sub>	Turn-Off Fall Time		--	3	--	nS
<b>Source- Drain Diode Characteristics</b>						
V <sub>SD</sub>	Forward on voltage	I <sub>SD</sub> =3A,V <sub>GS</sub> =0V	--	0.81	1.20	V
t <sub>rr</sub>	Reverse Recovery Time	T <sub>J</sub> =25°C,I <sub>SD</sub> =3A, V <sub>GS</sub> =0V	--	8.1	--	nS
Q <sub>rr</sub>	Reverse Recovery Charge	di/dt=100A/μs		3.4		nC

NOTE:

① Repetitive rating; pulse width limited by max. junction temperature.

② Pulse width ≤ 300μs; duty cycle ≤ 2%.

Typical Characteristics

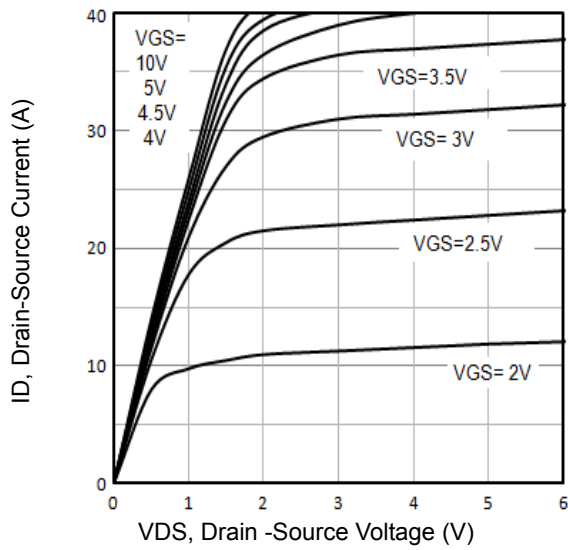


Fig1. Typical Output Characteristics

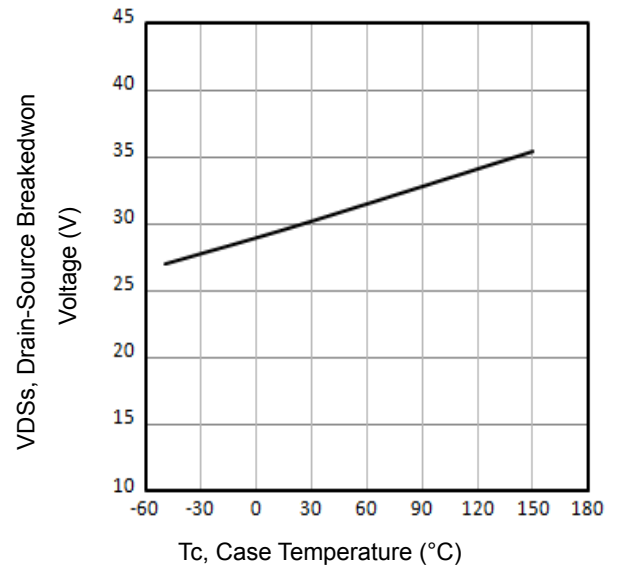


Fig2. Drain-source breakdown voltage

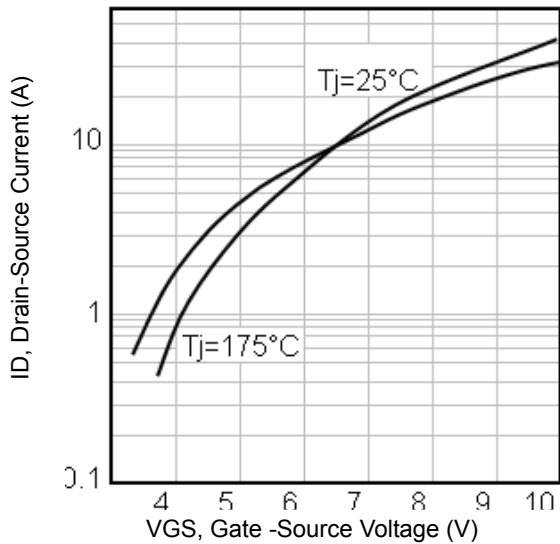


Fig3. Typical Transfer Characteristics

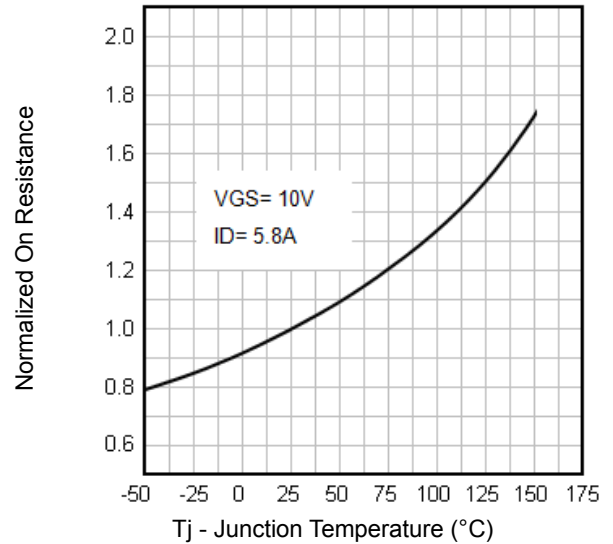


Fig4. Normalized On-Resistance Vs. Temperature

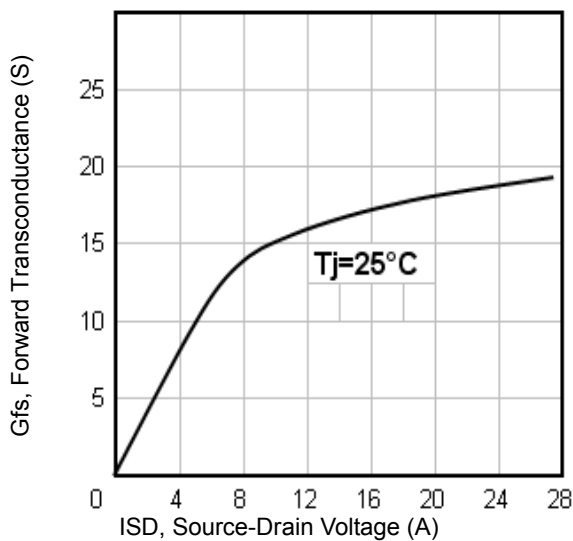


Fig5. Typical Forward Transconductance Vs. Drain Current

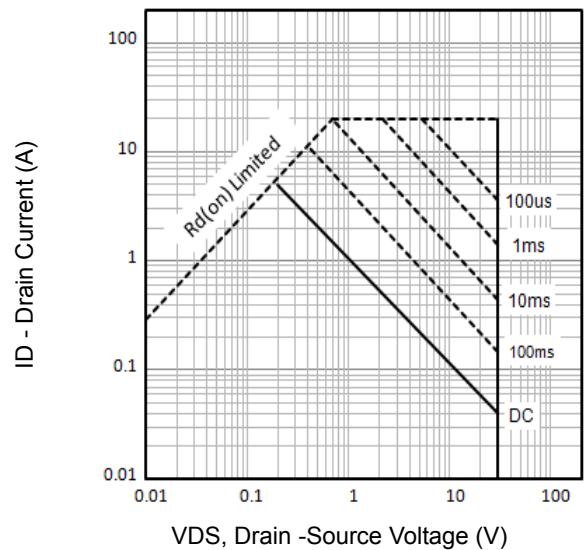


Fig6. Maximum Safe Operating Area

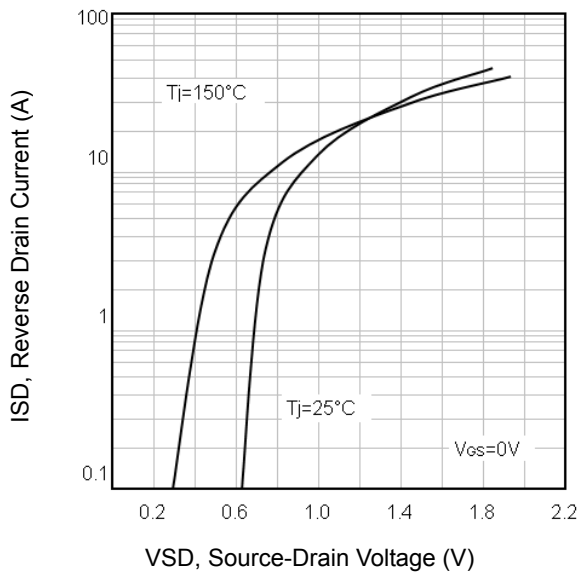


Fig7. Typical Source-Drain Diode Forward Voltage

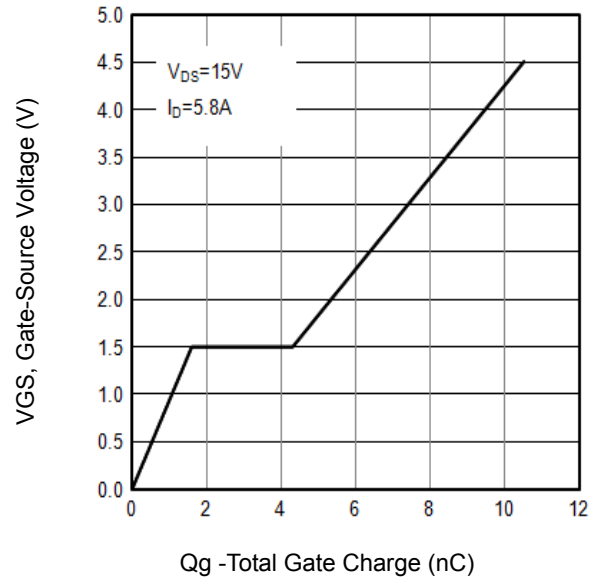


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

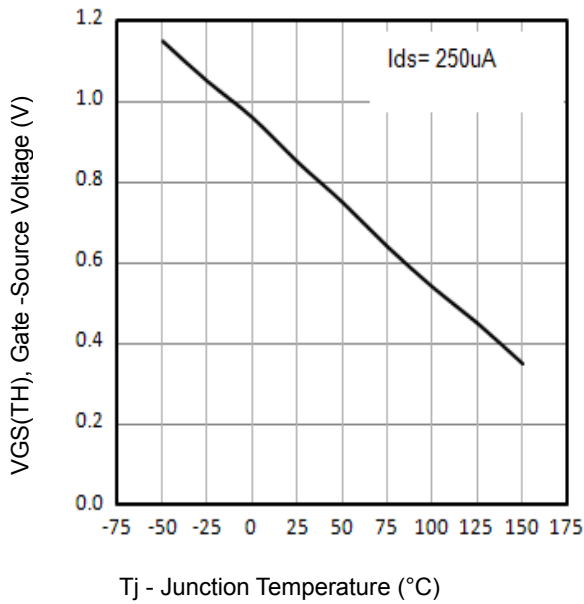


Fig9. Threshold Voltage Vs. Temperature

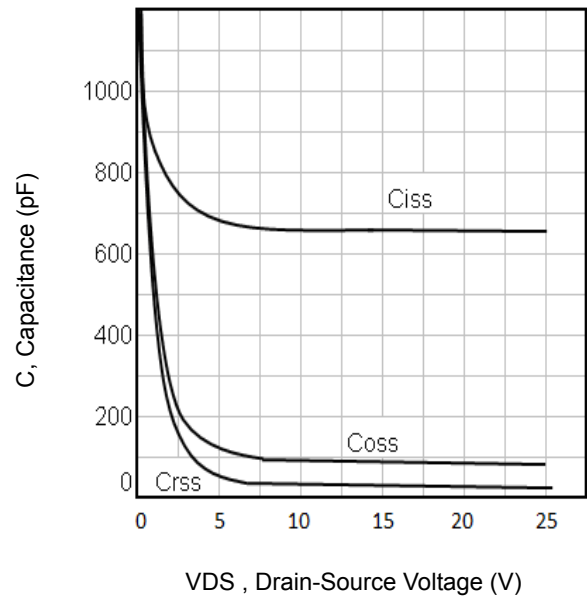


Fig10. Typical Capacitance Vs. Drain-Source Voltage

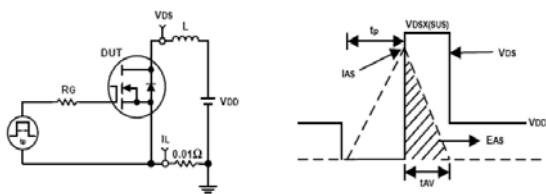


Fig11. Unclamped Inductive Test Circuit and waveforms

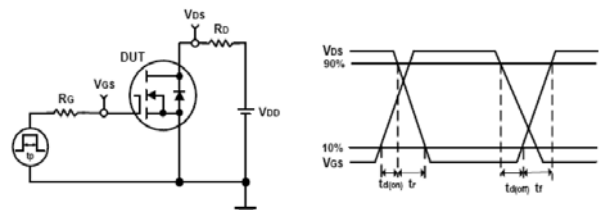
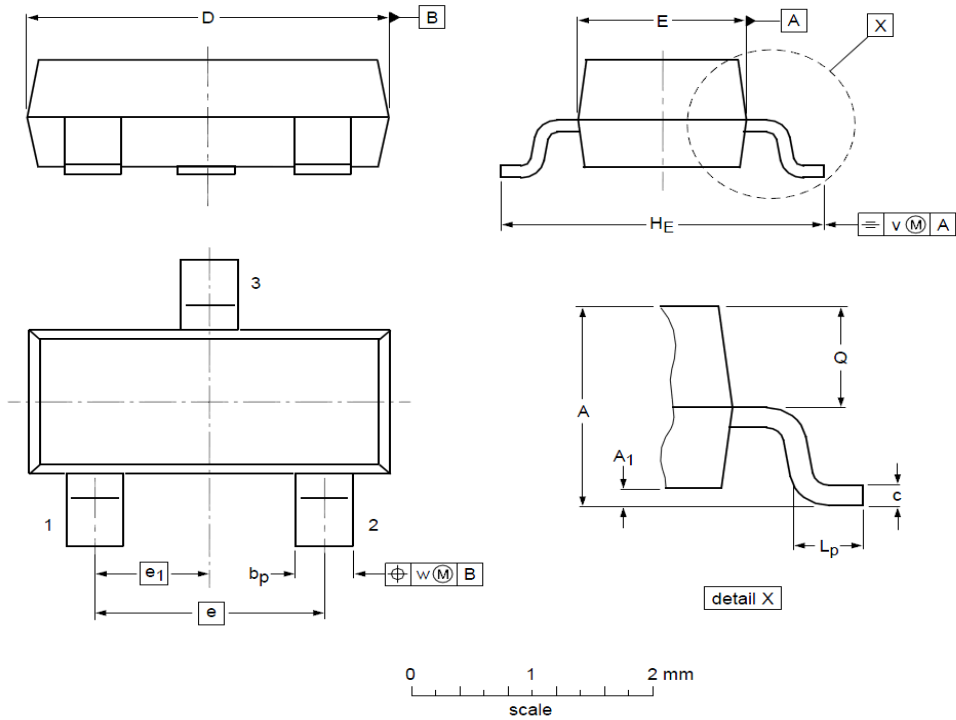


Fig12. Switching Time Test Circuit and waveforms

SOT23 Package Outline Data



DIMENSIONS ( unit : mm )

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.03	1.10	A <sub>1</sub>	0.01	0.05	0.10
b <sub>p</sub>	0.38	0.42	0.48	c	0.09	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e <sub>1</sub>	--	0.95	--
H <sub>E</sub>	2.10	2.40	2.50	L <sub>p</sub>	0.15	0.23	0.45
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				

Order Information

Product	Marking	Package	Packaging	Min Unit Quantity
VS3400BC	VS30	SOT23	3000/Reel	6000

Customer Service

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